

Max-Planck-Institut für Plasmaphysik, EURATOM Association Micro-chemical analysis of highly heat loaded **CFC/Cu interfaces from Tore Supra and Wendelstein 7-X**

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Motivation

- HHF tests to evaluate the expected lifetime of Tore Supra TPL elements covered with different types of CFC N11
- Component S390 showed a higher failure rate after HHF testing in GLADIS
- chemical • Micro investigations were performed on metallographically prepared cross sections of the CFC/Cu interface to check whether the bonding itself could be made responsible for the failure
- Comparison to W7-X advanced CFC/Cu bonding



SIMS

Secondary Ion Mass Spectrometry measurements were performed to visualize the spatial distribution of the alloying elements in the interfacial region

S390 Tile16: Tore Supra

CFC N11-98, slightly degraded

200 cycles

3000 cycles

has never been installed in TS before

10 MW/m²,

8 MW/m².

no defect after loading

S703 Tile16: Tore Supra

CFC N11-92, as specified has never been installed in TS before 10 MW/m². 200 cycles 8 MW/m², 3000 cycles no defect after loading

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improved AMC bonding as delivered

4S-045 t3: W7-X

10 MW/m², 5000 cycles

no defect after loading





















XPS

X-ray Photoelectron Spectroscopy measurements applied to determine the carbidic and metallic chemical states of titanium only carbidic Ti detected



Conclusions



Ti











Tore Supra TPL elements:

- 3000 cycles at 8 MW/m² performed, two elements covered with different N11 qualities
- Significantly different failure occurrence
- Differences in chemical composition of AMC bonding excluded as reason for failure
- Scatter in N11 quality confirmed as potential failure reason

Progress of W7-X bonding:

- Laser structuring better defined
- AMC bonding with improved elemental composition (addition of Si) [1]

[1] Eidenberger et. al., Advanced engineering materials 2006, 8, No. 11, p.1092



• No Si addition (Si signal low and not together with Ti)



- Ti evenly distributed
- Additional alloyed with Si
- Better defined cones

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